ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® MAterial Composition Dec © Copyright 2005. IPC, Bannockt international and Pan-American co	ourn. Illinois. All rights reserved	under both This doc	rument is a declaration entry, the declaration en	on of the substance ncompasses all low	es within the manufactur ver level materials for wl	er listed item. Note hich the manufactur	: if the item is an a rer has engineering	ssembly with lower responsibility.		
IPC Web Site for Information on I   http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information						
Supplier Information										
Company name*	ny name* Company unique ID			ority		Response Date*				
onsemi						2023-06-08				
Contact Name	Title - Contact		Phone - Contac	Phone - Contact*			Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance		NA			Product-Env-Stewards@onsemi.com				
Authorized Representative*	I Representative* Title - Representative		Phone - Representative*			Email - Representative*				
Product-Env-Stewards		NA			Product-Env-Stewards@onsemi.com					
Requester Item Number Mfr Item	Number Mfr Item Name	Mfr Item Name		Version	Manufacturing Site	Weight*	UOM	Unit Type		
FAN23S	V06MPX 6A 18V PoL Reg	gulators	2023-06-08		PBB	83.149	mg	Each		
Manufacturing Proccess Information	·				·					
Terminal Plating / Grid Array Material	erminal Base Alloy	J-STD-020 MSL Rating	Peak Proce	ess Body Temperat	ture Max Time at Peak	Temperature Nur	nber of Reflow Cy	cles		
Matte Tin (Sn) - annealed CU Alloy 1		1	260	С	30	seconds 3				
Comments										
evel 1 - maximum time at peak temperature during so	Idering is 10-30 seconds									
or more information regarding material composition	6									

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.14	mg	Supplier	Silicon (Si)	7440-21-3		1.14	mg
Die Attach Solder	1.362	mg	Supplier	Silver (Ag)	7440-22-4		0.034	mg
			А	Lead (Pb)	7439-92-1	7a	1.2599	mg
			Supplier	Tin (Sn)	7440-31-5		0.0681	mg
Lead Frame	30.983	mg	Supplier	Silver (Ag)	7440-22-4		0.282	mg
			Supplier	Zinc (Zn)	7440-66-6		0.04	mg
			Supplier	Iron (Fe)	7439-89-6		0.744	mg
			Supplier	Copper (Cu)	7440-50-8		29.917	mg
Mold Compound-Black	46.6	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'- tetramethylbiphenyl	85954-11-6		4.194	mg
			Supplier	Carbon Black (C)	1333-86-4		0.466	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.008	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.932	mg
Plating	1.78	mg	Supplier	Tin (Sn)	7440-31-5		1.78	mg
Vire Bond - Au	0.684	mg	Supplier	Gold (Au)	7440-57-5		0.684	mg
Wire Bond - Cu	0.6	mg	Supplier	Palladium (Pd)	7440-05-3		0.012	mg
			Supplier	Copper (Cu)	7440-50-8		0.588	mg